

International Application No.: PCT/JP2005/006608  
U.S. Patent Application No.: Unknown  
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**IN THE ABSTRACT:**

Please replace the Abstract of the Disclosure originally filed with the above-identified patent application with the following new Abstract of the Disclosure:

## ABSTRACT OF THE DISCLOSURE

A surface acoustic wave filter includes a device chip, one principal surface of a piezoelectric substrate having a wiring pattern including IDTs and pads electrically connected to the IDTs, that is disposed so as to oppose a mount board, with the pads being electrically connected to lands of the mount board through bumps. A resin film covers the other principal surface of the piezoelectric substrate and the principal surface of the mount board to seal the device chip. In the piezoelectric substrate, the area of the one principal surface is greater than the area of the other principal surface.